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FDP26N40 N-Channel UniFETTM MOSFET 400 V, 26 A, 160 mΩ

Features

- $R_{DS(on)}$ = 130 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 13 A
- Low Gate Charge (Typ. 48 nC)
- Low C_{rss} (Typ. 30 pF)
- 100% Avalanche Tested
- RoHS Compliant

Applications

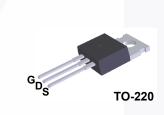
- Uninterruptible Power Supply
- AC-DC Power Supply

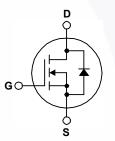
November 2013

FDP26N40 — N-Channel UniFETTM MOSFET

Description

UniFETTM MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





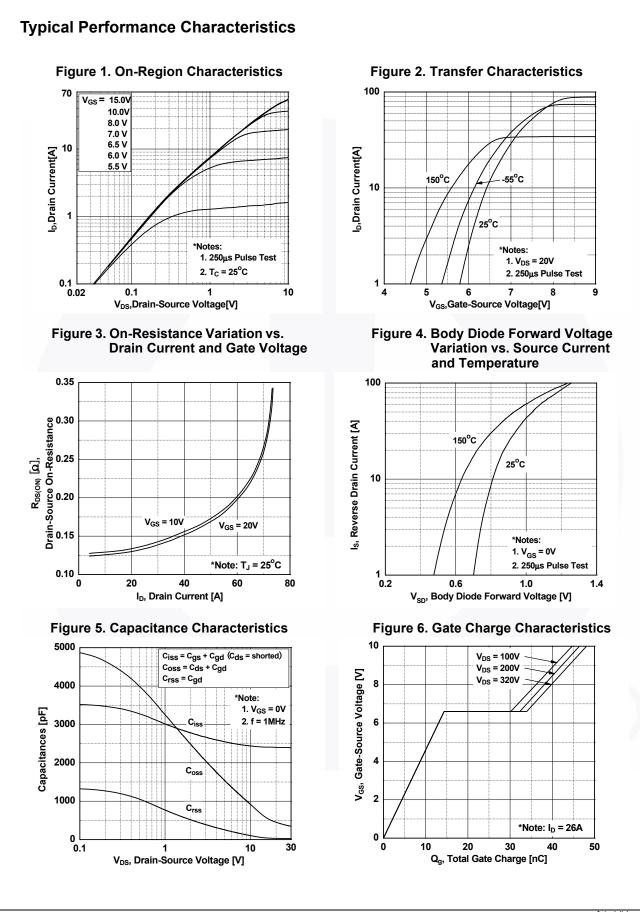
MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter			FDP26N40	Unit
V _{DSS}	Drain to Source Voltage			400	V
V _{GSS}	Gate to Source Voltage			±30	V
I _D	Drain Current	- Continuous (T _C = 25 ^o C)		26	
		- Continuous (T _C = 100 ^o C)		15.6	A
I _{DM}	Drain Current	- Pulsed (No	ote 1)	104	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)			1352	mJ
I _{AR}	Avalanche Current (Note 1)		ote 1)	26	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)		ote 1)	26.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		ote 3)	4.5	V/ns
P _D	Power Dissipation	$(T_{\rm C} = 25^{\rm o}{\rm C})$		265	W
		- Derate Above 25°C		2.0	W/ºC
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		s	300	°C

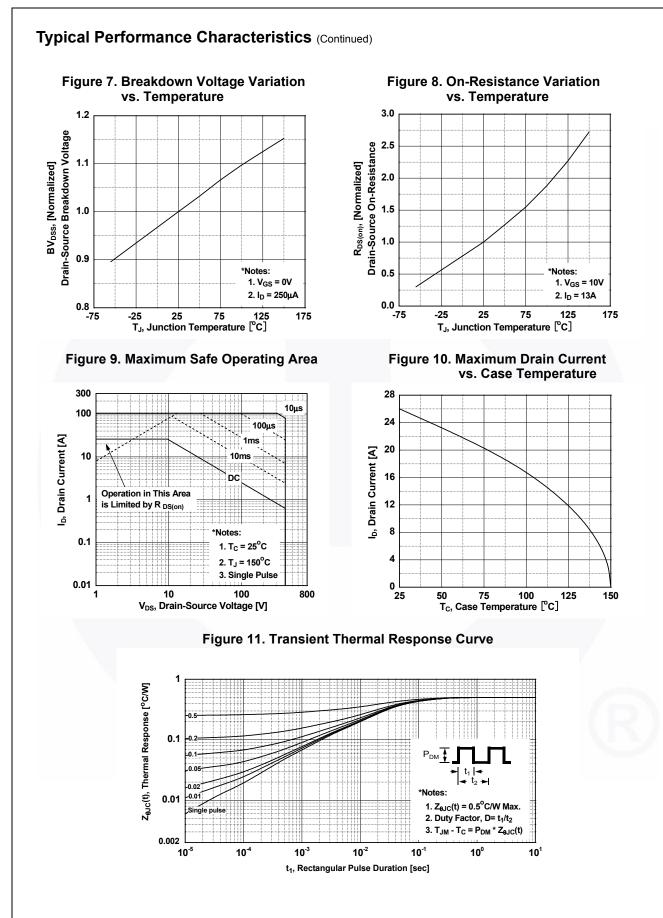
Thermal Characteristics

Symbol	Parameter	FDP26N40	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.5	°C/W
R_{\thetaJA}	Thermal Resistance, Junction to Ambient, Max.	62.5	°C/W

0 FDP26N40	Package	Packing Method	Reel Size	Iap	e Width	Qua	ntity
	TO-220	Tube	N/A		N/A	50 u	units
Characteristics T _c = 2	5°C unless of	herwise noted.					
Parameter		Test Conditio	ons	Min.	Тур.	Max.	Unit
eristics							
Drain to Source Breakdown Volta	age I _C	₀ = 250 μA, V _{GS} = 0 V,	T _J = 25 ^o C	400	-	-	V
Breakdown Voltage Temperature Coefficient		₀ = 250 μA, Reference	d to 25 ^o C	-	0.5	-	V/ºC
Zero Gate Voltage Drain Current		$V_{DS} = 400 V, V_{GS} = 0 V$		-	-	1	μA
Cato to Rody Loakago Current				-	-		n۸
Gate to Body Leakage Current	V	$_{\rm GS}$ = ±30 V, V _{DS} = 0 V		-	-	±100	nA
eristics							
Gate Threshold Voltage	V	/ _{GS} = V _{DS} , I _D = 250 μA		3.0	-	5.0	V
				-	0.13	0.16	Ω
Forward Transconductance				-	25.5	-	S
aracteristics					1		
			_	2400	3185	pF	
			_	-			pF
	f	= 1 MHz	_	-			pF
	N	(- 220 \/ - 26 A		-		60	nC
-		$V_{DS} = 320 \text{ V}, I_D = 26 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4)		-		-	nC
				-	20	-	nC
haracteristics					45	100	
	v	V_{DD} = 200 V, I_D = 26 A, V_{GS} = 10 V, R_G = 25 Ω					ns ns
							ns
,			(Note 4)				ns
			(Note 4)	- /	00	140	110
	ouroo Diada F	anward Current				26	•
				-	-	-	A
				-	-		A V
							ns μC
	Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Body Leakage Current Pristics Gate Threshold Voltage Static Drain to Source On Resist Forward Transconductance aracteristics Input Capacitance Output Capacitance Output Capacitance Reverse Transfer Capacitance Total Gate Charge at 10V Gate to Source Gate Charge Gate to Drain "Miller" Charge haracteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time e Diode Characteristics Maximum Continuous Drain to Source	Breakdown Voltage Temperature Ic Coefficient V Zero Gate Voltage Drain Current V Gate to Body Leakage Current V Pristics V Gate Threshold Voltage V Static Drain to Source On Resistance V Forward Transconductance V aracteristics Input Capacitance Input Capacitance V Output Capacitance V Gate to Drain "Miller" Charge V Baracteristics V Gate to Drain "Miller" Charge V Maracteristics V Turn-On Delay Time V Turn-Off Delay Time V Turn-Off Fall Time V Maximum Continuous Drain to Source Diode Forward V Orain to Source Diode Forward Voltage V Crain to Source Diode Forward Voltage V	Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, ReferenceZero Gate Voltage Drain Current $V_{DS} = 400 \ V, V_{GS} = 0 \ V$ Gate to Body Leakage Current $V_{GS} = \pm 30 \ V, V_{DS} = 0 \ V$ Gate to Body Leakage Current $V_{GS} = \pm 30 \ V, V_{DS} = 0 \ V$ eristics $V_{GS} = \pm 30 \ V, V_{DS} = 0 \ V$ Gate Threshold Voltage $V_{GS} = \pm 30 \ V, V_{DS} = 0 \ V$ Static Drain to Source On Resistance $V_{GS} = 10 \ V, I_D = 13 \ A$ Forward Transconductance $V_{DS} = 20 \ V, I_D = 13 \ A$ Input Capacitance $V_{DS} = 25 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$ Nutre Capacitance $V_{DS} = 25 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$ Reverse Transfer Capacitance $V_{DS} = 320 \ V, I_D = 26 \ A, V_{GS} = 10 \ V$ Gate to Drain "Miller" Charge $V_{DD} = 200 \ V, I_D = 26 \ A, V_{GS} = 10 \ V, R_G = 25 \ \Omega$ haracteristicsTurn-On Rise TimeTurn-Off Delay Time $V_{DS} = 10 \ V, R_G = 25 \ \Omega$ Turn-Off Fall Time $V_{GS} = 10 \ V, R_G = 25 \ \Omega$ Maximum Continuous Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentDrain to Source Diode Forward Voltage $V_{GS} = 0 \ V, I_{SD} = 26 \ A, Reverse Recovery TimeV_{GS} = 0 \ V, I_{SD} = 26 \ A, Reverse Recovery Time$	Breakdown Voltage Temperature CoefficientII <td>Breakdown Voltage Temperature Coefficient$I_D = 250 \ \mu$A, Referenced to 25°C-Zero Gate Voltage Drain Current$V_{DS} = 400 \ V, V_{GS} = 0 \ V$-Gate to Body Leakage Current$V_{GS} = 320 \ V, T_C = 125^{\circ}$C-Gate to Body Leakage Current$V_{GS} = \pm 30 \ V, V_{DS} = 0 \ V$-eristicsGate Threshold Voltage$V_{GS} = V_{DS}, I_D = 250 \ \mu$A3.0Static Drain to Source On Resistance$V_{GS} = 10 \ V, I_D = 13 \ A$-Forward Transconductance$V_{DS} = 20 \ V, I_D = 13 \ A$-aracteristicsInput CapacitanceOutput Capacitance$V_{DS} = 25 \ V, V_{GS} = 0 \ V, f = 1 \ HHz$-Total Gate Charge at 10V$V_{DS} = 320 \ V, I_D = 26 \ A, V_{GS} = 10 \ V$-Gate to Drain "Miller" Charge$V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, V_{CS} = 10 \ V, V_{CS} = 10 \ V, V_{CS} = 25 \ \Omega$-Turn-On Delay Time$V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$-Turn-Off Delay Time$V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$-Turn-Off Fall Time$V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$-turn-Off Fall Time$V_{OS} = 0 \ V, I_S = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$-turn-Off Fall Time$V_{OS} = 0 \ V, I_S = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$-turn-Off Fall Time$V_{OS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S$</td> <td>$\begin{array}{c c c c c c c c c c c c c c c c c c c$</td> <td>$\begin{array}{l l} Breakdown Voltage Temperature Coefficient & I_D = 250 \ \mu A, Referenced to 25^{\circ}C & - & 0.5 & - & 0.5 \\ \hline V_{DS} = 400 \ V, \ V_{GS} = 0 \ V & - & - & 1 \\ \hline V_{DS} = 320 \ V, \ T_C = 125^{\circ}C & - & - & 10 \\ \hline Gate to Body Leakage Current & V_{GS} = ±30 \ V, \ V_{DS} = 0 \ V & - & - & \pm 100 \\ \hline eristics & &$</td>	Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, Referenced to 25° C-Zero Gate Voltage Drain Current $V_{DS} = 400 \ V, V_{GS} = 0 \ V$ -Gate to Body Leakage Current $V_{GS} = 320 \ V, T_C = 125^{\circ}$ C-Gate to Body Leakage Current $V_{GS} = \pm 30 \ V, V_{DS} = 0 \ V$ -eristicsGate Threshold Voltage $V_{GS} = V_{DS}, I_D = 250 \ \mu$ A3.0Static Drain to Source On Resistance $V_{GS} = 10 \ V, I_D = 13 \ A$ -Forward Transconductance $V_{DS} = 20 \ V, I_D = 13 \ A$ -aracteristicsInput CapacitanceOutput Capacitance $V_{DS} = 25 \ V, V_{GS} = 0 \ V, f = 1 \ HHz$ -Total Gate Charge at 10V $V_{DS} = 320 \ V, I_D = 26 \ A, V_{GS} = 10 \ V$ -Gate to Drain "Miller" Charge $V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, V_{CS} = 10 \ V, V_{CS} = 10 \ V, V_{CS} = 25 \ \Omega$ -Turn-On Delay Time $V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$ -Turn-Off Delay Time $V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$ -Turn-Off Fall Time $V_{DD} = 200 \ V, I_D = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$ -turn-Off Fall Time $V_{OS} = 0 \ V, I_S = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$ -turn-Off Fall Time $V_{OS} = 0 \ V, I_S = 26 \ A, V_{CS} = 10 \ V, R_G = 25 \ \Omega$ -turn-Off Fall Time $V_{OS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S = 26 \ A, V_{CS} = 0 \ V, I_S$	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{l l} Breakdown Voltage Temperature Coefficient & I_D = 250 \ \mu A, Referenced to 25^{\circ}C & - 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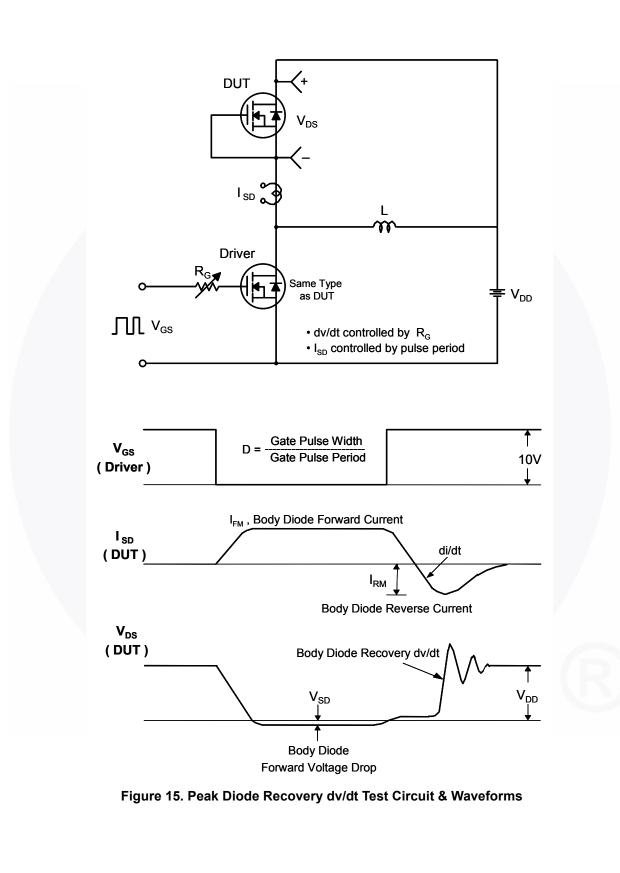


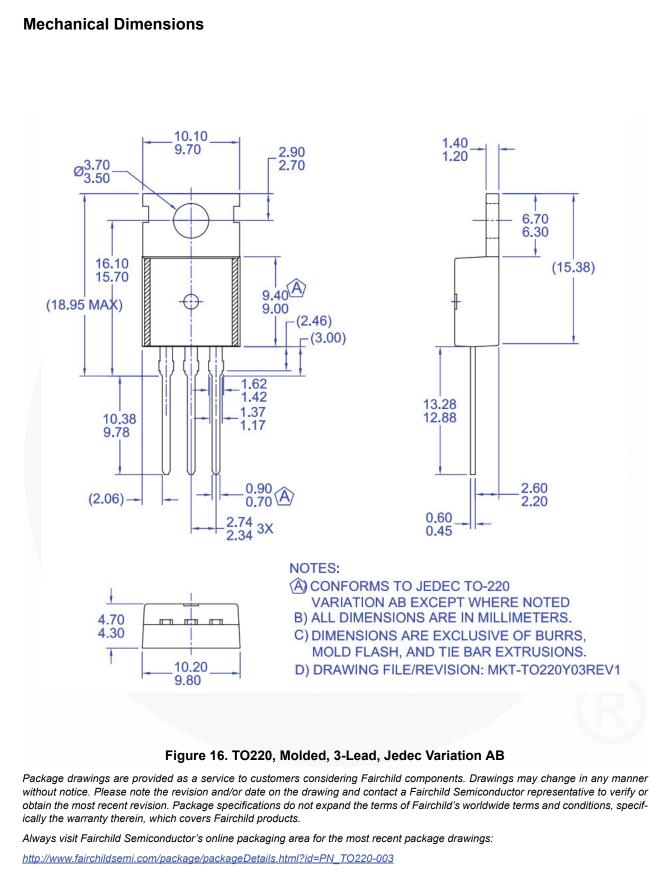
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 V_{GS} ξ א Q_g FV_{DS} Q_{gd} Q_{gs} • DUT I_G = const. Charge Figure 12. Gate Charge Test Circuit & Waveform R VDS V_{DS} 90% ο V_{DD} GS R_{G} 10% V_{GS} DUT V_{GS} ∏ 0 Figure 13. Resistive Switching Test Circuit & Waveforms L $E_{AS} = \frac{1}{2} L I_{AS}^2$ V_{DS} $\mathsf{BV}_{\mathsf{DSS}}$ ID o I_{AS} R_{G} ŧν_{DD} $I_{D}(t)$ V_{GS}] $V_{DS}(t)$ V_{DD} DUT Time t_p Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

FDP26N40 — N-Channel UniFETTM MOSFET

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